



maN-2403 Monitor Results

February 01, 2011

Process Conditions

Substrate:

- ~1” silicon wafer piece

Coat:

- maN - 2403 resist
- 4000 RPM, 2000 RPM / sec, 60sec
- 90°C hot plate bake for 1 minutes
- Thickness: 291nm (measured on the Nanospec reflectometer)

Develop:

- TMAH immersion for 70 seconds
- DI water rinse for 60 seconds
- N₂ blow dry

Thickness vs. Dose

